

SPECIFICATION FOR LCD MODULE

MODULE NO: AFK320240A0-3.5N12NTH **REVISION NO: V02**

Customer's Approval:		
	SIGNATURE	DATE
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Records of Revision

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2016-02-06		V01	First Issue	
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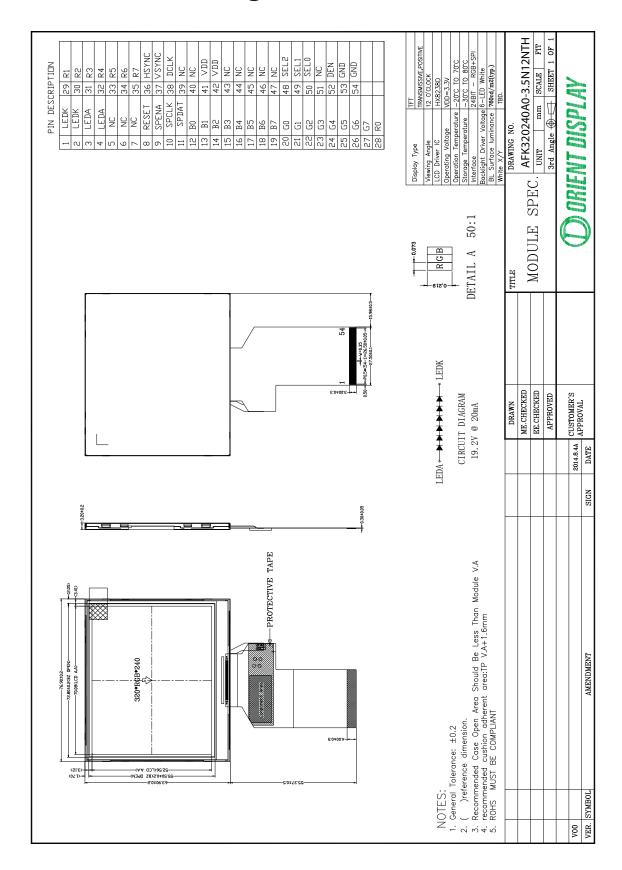
Contents

1. General Specification	4
2. Mechanical Drawing	5
3. Block Diagram	6
4. Interface Pin Function.	7
5. Absolute Maximum Ratings	8
6. Electrical Characteristics	9
7. Optical Characteristics	11
8. Timing Characteristics	14
9. Standard Specification for Reliability	17
10. Specification of Quality Assurance	19
11. Handling Precaution	28
12. Packing Method.	28

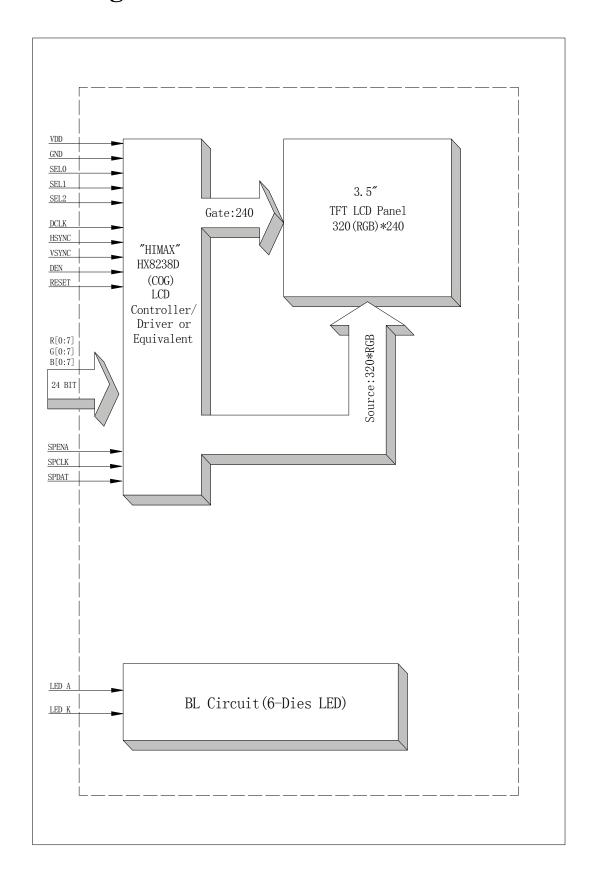
1. General Specification

Item	Contents	Unit
LCD TYPE	TFT/TRANSMISSIVE	
MODULE SIZE (W*H*T)	76.90*63.90*3.20	MM
ACTIVE SIZE (W*H)	70.08*52.56	MM
PIXEL PITCH (W*H)	0.219*0.219	MM
NUMBER OF DOTS	320*240	
DIVER IC	HX8238D	
INTERFACE TYPE	24BIT RGB+SPI	
TOP POLARIZER TYPE	ANTI-GLARE	
RECOMMEND VIEWING DIRECTION	12	O'CLOCK
GRAY SCALE INVERSION DIRECTION	6	O'CLOCK
BACKLIGHT TYPE	6-DIES WHITE LED	
TOUCH PANEL TYPE	WITHOUT	

2. Mechanical Drawing



3. Block Diagram



4. Interface Pin Function

Pin No.	Symbol	Description
1	LEDK	Cathode of LED backlight
2	LEDK	Cathode of LED backlight
3	LEDA	Anode of LED backlight
4	LEDA	Anode of LED backlight
5	NC(YU)	No connect
6	NC(XR)	No connect
7	NC	No connect
8	RESET	RESET PIN
9	SPENA	Chip select of serial interface
10	SPCLK	Clock pin of serial interface
11	SPDAT	Data input pin of serial interface
12~19	B0~B7	Blue data bus
20~27	G0~G7	Green data bus
28~35	R0~R7	Red data bus
36	HSYNC	Horizontal sync signal; negative polarity
37	VSYNC	Vertical sync signal; negative polarity
38	DCLK	Clock signal; latching data at the falling edge
39	NC	Touch panel control PIN: XL
40	NC	Touch panel control PIN: YU
41	VDD	Power supply
42	VDD	Power supply
43	NC(YD)	No connect
44	NC(XL)	No connect
45	NC	No connect
46	NC	No connect
47	NC	No connect
48	SEL2	
49	SEL1	Interface mode select(note)
50	SEL0	
51	NC	No connect
52	DEN	Display enable pin from controller
53	GND	Power ground
54	GND	Power ground

Note:

- 1. The mode control (SEL2) not use ,it can't control CCIR601 interface, If not use CCIR601 ,it can floating.
- 2. For digital RGB input data format, both SYNC mode and DE+SYNC mode are supported. If DE signal is fixed low, SYNC mode is used. Otherwise, DE+SYNC mode is used. Suggest used SYNC mode!!Suggest the DE signal usually pull low.
- 3. IF select serial RGB or CCIR601/656 input mode is selected, only DX0-DX7 used, and the other short to GND, Only selected serial RGB、CCIR601/656 interface, DX BUS will enable, Digital input mode DX0 is LSB and DX7 is MSB.

interface select table

SEL2	SEL1	SEL0	Interface Mode
0	0	0	Parallel-RGB Data format interface
U	0 0 0		(only support stripe type color filter)
0	0	1	Serial-RGB data format
0	1	0	CCIR 656 data format (640RGB)
0	1	1	CCIR 656 data format (720RGB)
1	0	0	YUV mode A data format(Cr-Y-Cb-Y)
1	0	1	YUV mode A data format(Cr-Y-Cb-Y)
1	1	0	YUV mode B data format(Cb-Y-Cr-Y)
1	1	1	YUV mode B data format(Cb-Y-Cr-Y)

5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply voltage for analog	VDD	-0.3	4.5	V
Supply voltage for logic	VDD	-0.3	4.5	V
Supply current (One LED)	I _{LED}		30	mA
Operating temperature	T_{OP}	-20	+70	°C
Storage temperature	T _{ST}	-30	+80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

6. Electrical Characteristics

6.1 Input Power

Item	Symbol	Min	Тур.	Max	Unit	Applicable terminal
Supply Voltage for Analog	VDD	3.0	3.3	3.6	V	
Supply Voltage for Logic	VDD	3.0	3.3	3.6	V	
Innut Waltaga	V_{IL}	GND	-	0.3VDD	V	
Input Voltage	$ m V_{IH}$	0.7 VDD	1	VDD	V	
Input leakage Current	I_{LKG}	-1		1	μΑ	

6.2 Backlight Driving Conditions

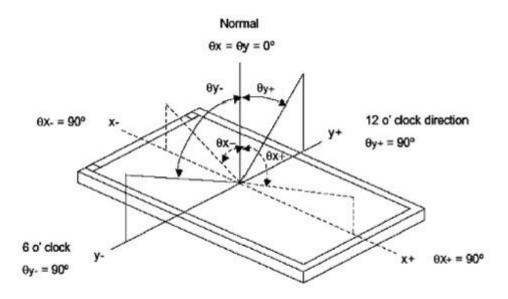
Idom	Cross had		Value	11:4	Remar	
Item	Symbol	Min.	Тур.	Max.	Unit	k
Voltage for LED Backlight	V _F	-	19.2	-	V	I _L =20mA
Current for LED Backlight	IL		20	30	mA	
Power Consumption	P		0.64		W	
LED Life Time		30,000	50,000		Hr	Note

Note: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25 $^{\circ}$ C

7. Optical Characteristics

LINEA	Л	CVMDOI	CONDITIONS	SPEC	IFICAT	ΓΙΟΝS	IINIIT	NOTE
IIEN			CONDITIONS	MIN	TYP.	MAX	UNIT	NOTE
Lumina	nce	L	I _L =20mA	600	760	920	Cd/m ²	
Contrast l	Ratio	CR	θ=0°	200	300			
Response Time		Ton	25℃		15	30	122 G	
		Toff	23 C		35	50	ms	
	Red	XR						
	Reu	YR						
	Green	XG						
CIE Color	Green	YG	Viewing normal					
Coordinate	Blue	Хв	angle					
	Diue	YB						
	White	Xw			TBD			
	winte	Yw			TBD			
	Hor. $ heta_{X+}$				60			
Viewing	Hor.	$ heta_{\scriptscriptstyle X-}$	CR≥10		60		Dagraa	
Angle Ver.	$\theta_{\scriptscriptstyle Y+}$	CK=10		50		Degree		
	vei.	$ heta_{\scriptscriptstyle Y-}$			60			
Uniformity	Un			80			%	

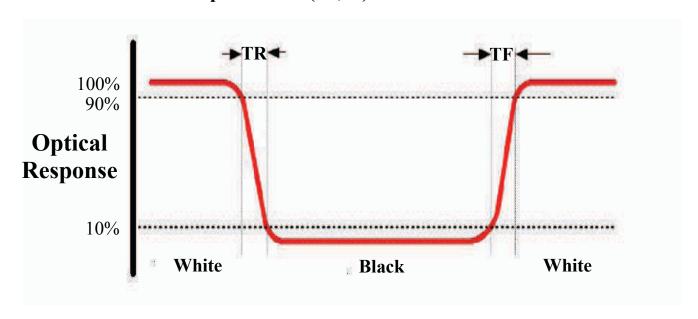
Note 1: Definition of Viewing Angle θx and θy :



Note 2: Definition of contrast ratio CR:

$$CR = \frac{Luminance of white state}{Luminance of black state}$$

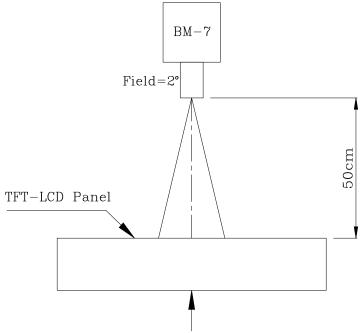
Note 3: Definition of Response Time(Tr,Tf)



Note 4: Definition of Luminance

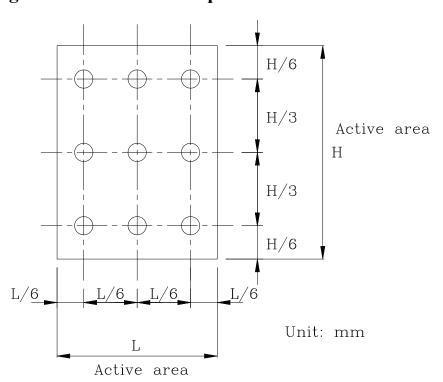
1 The Brightness Test Equipment Setup

Field=2° (As measuring "black" image, field=2° is the best testing condition)



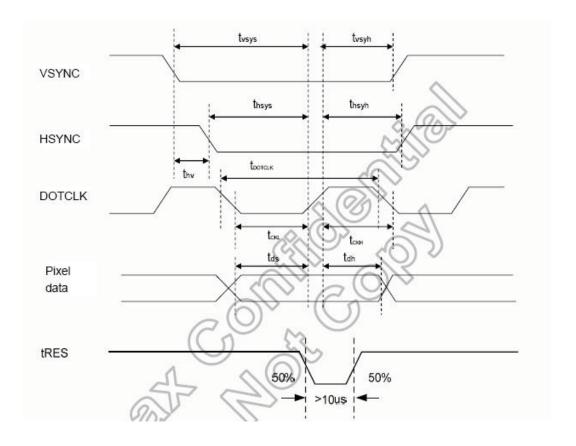
The center of the screen

2 The Brightness Test Point Setup



8. Timing Characteristics

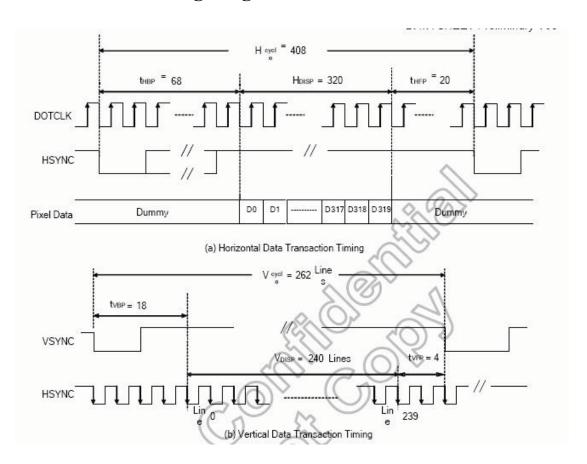
8.1 Pixel Timing Diagram



Characteristics	Symbol	Mi	n.	Тур.		Max.		Unit
	Symbol	24 bit	8 bit	24 bit	8 bit	24 bit	8 bit	Onit
DOTCLK Frequency	fDOTCLK	-	-	6.5	19.5	10	30	MHz
DOTCLK Period	tDOTCLK	100	33.3	154	51.3			ns
Vertical Sync Setup Time	tvsys	20	10			220	2	ns
Vertical Sync Hold Time	tvsyh	20	10	-	-		-	ns
Horizontal Sync Setup Time	thsys	20	10	-	-	190	-	ns
Horizontal Sync Hold Time	thsyh	20	10	B]	150			ns
Phase difference of Sync Signal Falling Edge	thv	1		479		240		tDOTCLK
DOTCLK Low Period	tCKL	50	15	-	-	-	-	ns
DOTCLK High Period	tCKH	50	15	21	-		-	ns
Data Setup Time	tds	12	10	<u>1</u> 2)	- 2	825	- 2	ns
Data hold Time	tdh	12	10	13	-	150	-	ns
Reset pulse width	tRES	1	0			-		μS

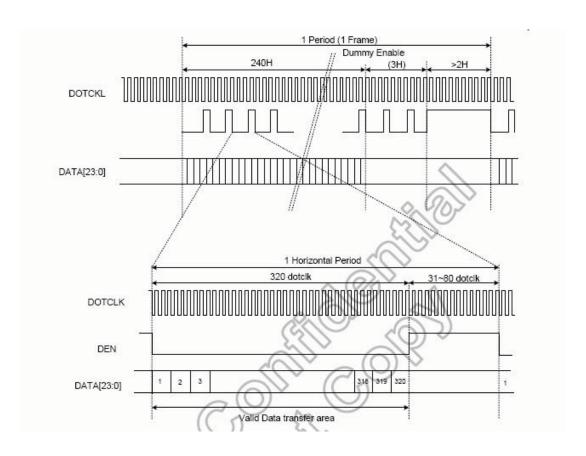
Note: External clock source must be provided to DOTCLK pin of HX8238-D. The driver will not operate if absent of the clocking signal.

8.2 SYNC mode Timing Diagram



Characteristics	Cumbal	Mi	n.	Ty	p.	Max.		Unit	
	Symbol	24 bit	8 bit	24 bit	8 bit	24 bit	8 bit	Ullit	
DOTCLK Frequen	cy_	fDOTCLK	(5)		6.5	19.5	10	30	MHz
DOTCLK Period	N/V	tDOTCLK)	100	33.3	154	51.3	200	329	ns
Horizontal Freque	ncy (Line)	/_fA\			14	.9	22	.35	KHz
Vertical Frequency	(Refresh)	< fV)	S(-	8	6	0	9	0	Hz
Horizontal Back P	orch	tHBP	-	22	68	204		8.76	tDOTCLK
Horizontal Front P	orch	tHFP	950	-	20	60		13 7 0	tDOTCLK
Horizontal Data Start Point		tHBP	72	275	68	204	- 20	322	tDOTCLK
Horizontal Blanking Period		tHBP + tHFP	144	200	88	264	188	949	tDOTCLK
Horizontal Display Area		HDISP	14	- 2	320	960	-	547	tDOTCLK
Horizontal Cycle	The state of the s	Hcycle		. 20	408	1224	450	1350	tDOTCLK
Vertical Back Pord	h	tVBP			18		-		Lines
Vertical Front Por	ch	tVFP	727		4		. 53	37	Lines
Vertical Data Star	t Point	tVBP	32	8	18		347		Lines
Vertical Blanking I	Period	tVBP + tVFP	() -	3	22		543		Lines
Madical Disales	NTSC	~			24	10	*		
Vertical Display Area	PAL	VDISP	22 .	8	280(PALM=0)		7	7.0	Lines
	PAL	0			288(PALM=1)				
Vertical Cycle	NTSC	Vaunia	3.7	8	262 313		350		Linco
Vertical Cycle	PAL	Vcycle	661						Lines

8.3 DE mode Timing Diagram



Characteristics	Symbol	Min.		Тур.		Max.		Unit
Characteristics	Syllibol	24-bit	8-bit	24- bit	8-bit	24-bit	8-bit	Olin
DOTCLK Frequency	fDOTCLK	- /	3/1	6.5	19.5	10	30	MHz
DOTCLK Period	tDOTCLK	100	33.3	154	51.3		-	ns
Horizontal Blanking Period	tHBP + tHFP	52	146	88	264	180	960	tDOTCLK
Horizontal Display Area	HDISP	- ,	S -	320	960	120	120	tDOTCLK
Horizontal Cycle	Hcycle	372	1106	408	1224	500	1920	tDOTCLK
Vertical Blanking Period	tVBP + tVFP	V 2		-		4	7	Lines
Vertical Display Area	VDISP	-	1	24	0	()2	-33	Lines
Vertical Cycle	Vcycle	24	2	ĵ		28	37	Lines

Note: The above parallel RGB interface timing sequence is for reference only. For the other interface timing sequence, please refer to the driver IC(HX8238D) data sheet.

9. Standard Specification for Reliability

9.1 Standard Specification for Reliability of LCD Module

No.	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles: -30° C for 30 minutes \rightarrow normal temperature for 5 minutes \rightarrow +80°C for 30 minutes \rightarrow normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range: 10Hz ~ 55Hz Amplitude of vibration: 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.
08	Packing drop test	According to ASTM-D-5327.
00	Electrical	Air: $\pm 4KV 150 pF/330\Omega 5$ times
09	Static Discharge	Contact: ±2KV 150pF/330Ω 5 time

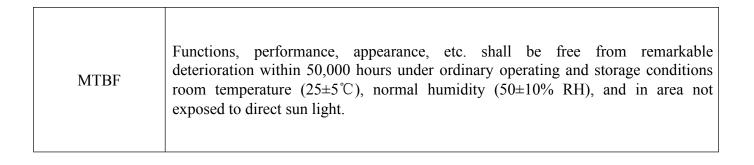
^{*}Sample size for each test item is 3~5pcs

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

9.3 MTBF



10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by ODNA.

10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single Time.
- The defects classify of AQL as following:

Major defect: AQL = 0.65Minor defect: AQL = 2.5Total defects: AQL = 2.5

10.3 Non-conforming Analysis & Deal With Manners

10.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

10.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

10.4 Agreement items

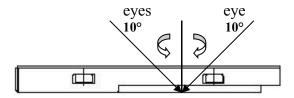
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

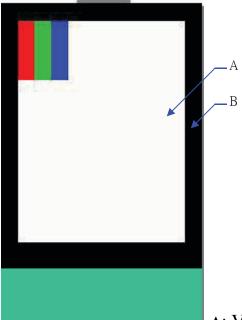
10.5 Standard of The Product Appearance Test

10.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5 °C Humidity: 60±10%RH



• Definition of area:



A: Viewing area B: Outside viewing area

10.5.2 Basic principle

- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.

10.6 Inspection Specification

NO.	Item		Cri	terion		AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker 			0.65	
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	 2.1 White and black or color spots on display ≤ 0.25mm, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm. 			2.5	
Touc Pane spots spots conta on (r	LCD and Touch Panel black spots, white	3.1 Round type: As follows: $\Phi = (X+Y)/2$ * Densely spaced: No		Size(mm) $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi \le 0.30$ $0.30 < \Phi$	Acceptable Q'ty Accept no dense 2 2 1 0 spots within 3mm.	2.5
	spots, white spots, contaminati on (non – display)	3.2 Line type: (As follows)	Length(mm) L≤3.0 L≤2.5	mg) Width(mm) $W \le 0.02$ $0.02 < W \le 0.05$ $0.03 < W \le 0.08$ $0.08 < W$	Acceptable Q'ty Accept no dense 2 Rejection o lines within 3mm.	2.5

NO.	Item	Criterion			
	D.1.	If bubbles are visible, judge using black spot specifications, not easy	Size $\Phi(mm)$ $\Phi \leq 0.20$	Acceptable Q'ty Accept no dense	
04	Polarizer bubbles	to find, must check in	$0.20 < \Phi \le 0.50$	3	2.5
		specify direction	$0.50 < \Phi \le 1.00$	2	
			1.00< Φ	0	_
			Total Q'ty	3	
05	Scratches	Follow NO.3 -2 Line Type.			
06	Chipped glass	x: Chip length y: Chip width z: k: Seal width t: Glass thickness the content of	x: Chip leng $x \le 1/8a$ x: $x \ge 1/8a$	chip	2.5

NO.	Item	Criterion	AQL
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:	
		y: Chip width x: Chip length z: Chip thickness	
		$y \le 0.5 \text{mm}$ $x \le 1/8 a$ $0 < z \le t$	
07	Glass crack	Non-conductive portion:	2.5
		y: Chip width x: Chip length z: Chip thickness	
		$y \le L \qquad \qquad x \le 1/8a \qquad \qquad 0 < z \le t$	
		 If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 7.2.3 Substrate protuberance and internal crack 	
		y: width x: length	
		$y \le 1/3L \qquad X \le a$	

NO.	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
09	Backlight elements	 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. 	2.5 2.5 0.65
10	Bezel	Bezel must comply with product specifications.	2.5
11	PCB、COB	 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. 	2.5 2.5 2.5 2.5 0.65
12	FPC	12.1 FPC terminal damage \leq 1/2 FPC terminal width and can not affect the function , we judge accept. 12.2 FPC alignment hole damage \leq 1/2 alignment area and can not affect the function , we judge accept.	2.5 2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle.13.2 No short circuits in components on PCB or FPC.	2.5 0.65

NO.	Item		Criterion		AQL
14	Touch Panel Chipped glass	k: Seal width t: 'L: Electrode pad leng 14.1 General glass of 14.1.1 Chip on panel z: Chip thickness Z≦t O Unit: mm	gth	x: Chip length x ≤ 1/8a	2.5
		z: Chip thickness	y: Chip width ≤ 1/2 k and not over	x: Chip length	
		z≦t	viewing area	x ≤ 1/8a	
		⊙ Unit: mm⊙ If there are 2 or m	nore chips, x is the total	length of each chip	

NO.	Item	Criterion	AQL		
15	Touch Panel(Fish eye、dent and bubble on film)	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.5		
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.			
17	Touch Panel Linearity	Less than 2.5% is acceptable.			
18	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5		
19	General appearance	 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 			

11. Handling Precaution

11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

- Store it in an ambient temperature of 25±10°C, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than 280±10°C and less than 3 sec during hand soldering.
- Rewiring: no more than 2 times.

12. Packing Method

----TBD